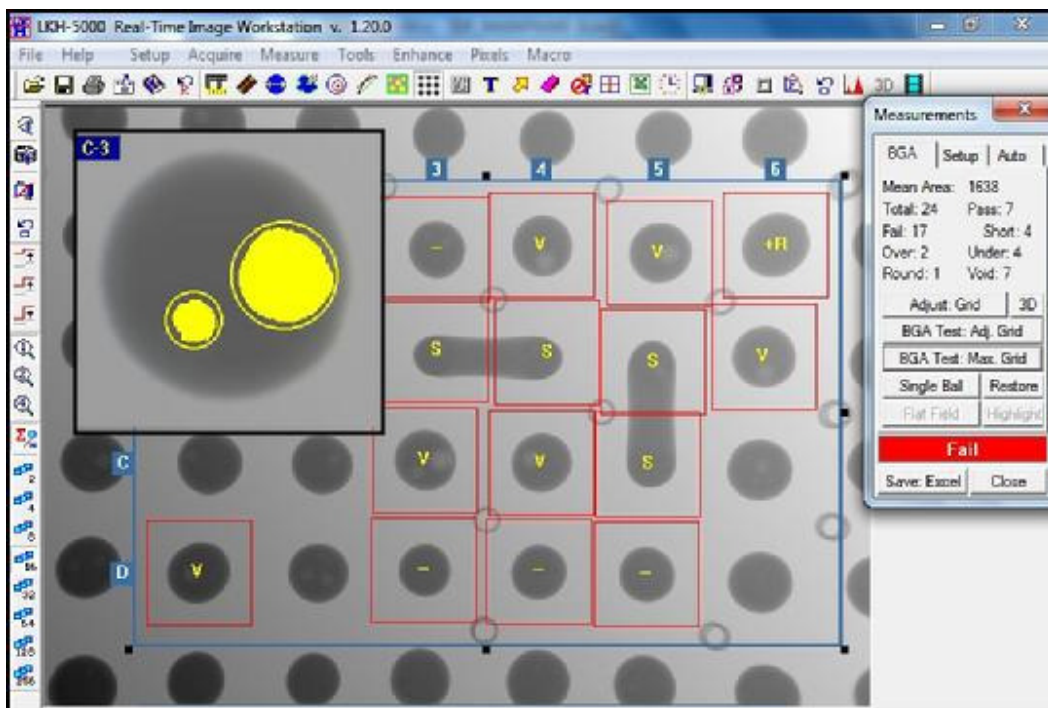


# LKH-5000



A high-performance software package for creating powerful X-ray workstations for analysis of electronic assemblies.

- Inspect BGA, Flip Chip and other surface mounted components.
- Analyze BGAs for voids, bridging, size, shape, and missing balls.
- Check dies for defects, such as voids, cracks and faulty wire bonds.



## System Requirements

Windows 10, 7, XP  
RS-170 video input  
USB frame grabber

## Live Image Processing

Frame Averaging  
Image Sharpening  
Zoom and Scroll  
Contour Relief  
Pseudo color  
Automatic Contrast

## Special LKH-5000 Features

Automatic BGA analysis  
Wire sweep measurements  
Drill-Hole X-Y offset

## Calibrated Measurements

Linear Distance  
Circle Diameter  
Percent Void  
Traced Area  
Pass/Fail reporting  
Save Data in Excel

## Analysis Features

Pixel Histogram  
Pixel Line Profiles  
Read Single Pixels  
Split-Screen Display  
Quad-View Display  
3-D Rendering

## Image Archiving

Save Image to Disk  
Video Recording  
Text Labeling